



Product Change Notification: DSNO-18SQTN760

Date:

03-Sep-2025

Product Category:

Switching Regulators

Notification Subject:

CCB 7580 Initial Notice: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

Affected CPNs:

[DSNO-18SQTN760_Affected_CPN_09032025.pdf](#)

[DSNO-18SQTN760_Affected_CPN_09032025.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	Unisem Chengdu Co.,Ltd (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Wire Material	Cu	Cu	CuPdAu
Die Attach Material	8290	8290	CDF215
Molding Compound Material	G770HP	G770HP	G631BQF

Lead-Frame Material	C194	C194	C7025
Lead-Frame Paddle Size	69x41mils	69x41mils	67x39mils
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.		
DAP Surface Prep	Spot Ag	Spot Ag	Ring Ag

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: November 2025

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	November 2025				
Work Week	18	19	20	21	22		45	46	47	48	49
Initial PCN Issue Date				X							
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: May 21, 2025: Issued initial notification.

September 03, 2025: Re-issued initial notification to update die-attach material from AP4300 to CDF215.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-18SQTN760-Qual_Plan.pdf

PCN_DSNO-18SQTN760_Pre and Post Change Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MIC2876-5.25YMT-T5

MIC2875-5.5YMT-T5

MIC2876-5.5YMT-T5

MIC2876-4.75YMT-T5

MIC2875-5.25YMT-T5

MIC2875-4.75YMT-T5

MIC2876-AYMT-T5

MIC2876-5.5YMT-TR

MIC2876-5.25YMT-TR

MIC2876-5.0YMT-TR

MIC2876-4.75YMT-TR

MIC2875-AYMT-T5

MIC2875-5.5YMT-TR

MIC2875-5.0YMT-TR

MIC2875-5.0YMT-T5

MIC2875-4.75YMT-TR

MIC2876-5.0YMT-T5

MIC2876-AYMT-TR

MIC2875-AYMT-TR

MIC2875-5.25YMT-TR

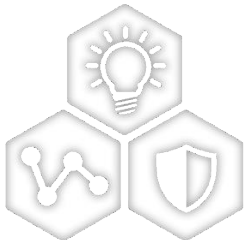
CCB 7580

Pre and Post Change Summary

PCN #: DSNO-18SQTN760

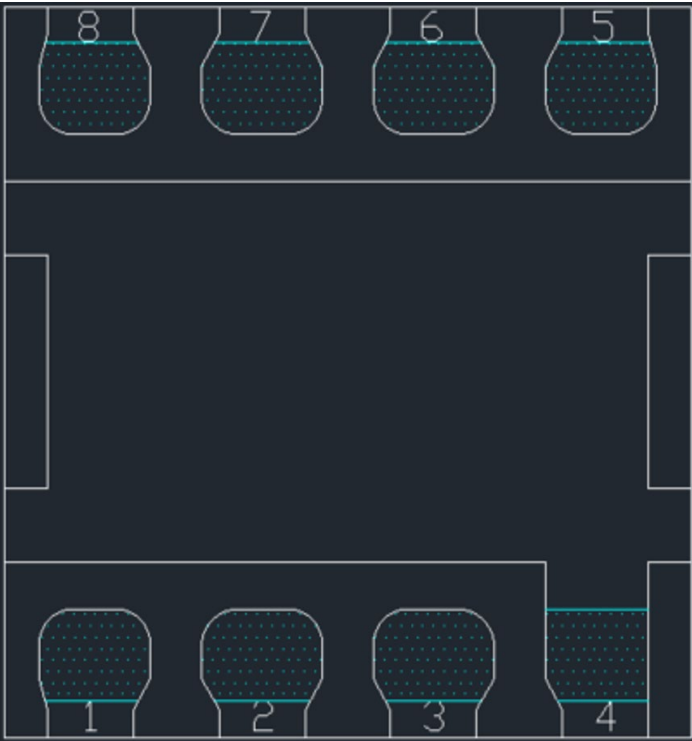
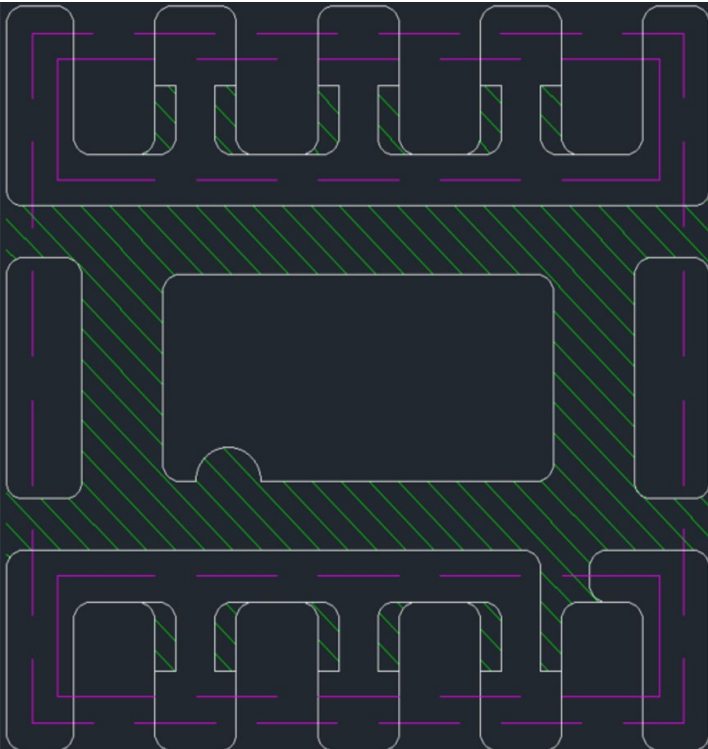


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Lead-Frame Comparison

UNIC	ATP7												
													
Note: Not-to-scale													
<table><tr><td>Lead-Frame Material</td><td>C194</td></tr><tr><td>DAP Surface Prep</td><td>Spot Ag</td></tr><tr><td>Lead-Frame Paddle Size</td><td>69x41mils</td></tr></table>	Lead-Frame Material	C194	DAP Surface Prep	Spot Ag	Lead-Frame Paddle Size	69x41mils	<table><tr><td>Lead-Frame Material</td><td>C7025</td></tr><tr><td>DAP Surface Prep</td><td>Ring Ag</td></tr><tr><td>Lead-Frame Paddle Size</td><td>67x39mils</td></tr></table>	Lead-Frame Material	C7025	DAP Surface Prep	Ring Ag	Lead-Frame Paddle Size	67x39mils
Lead-Frame Material	C194												
DAP Surface Prep	Spot Ag												
Lead-Frame Paddle Size	69x41mils												
Lead-Frame Material	C7025												
DAP Surface Prep	Ring Ag												
Lead-Frame Paddle Size	67x39mils												



QUALIFICATION PLAN SUMMARY

PCN#: DSNO-18SQTN760

**Date:
April 08, 2025**

**Qualification of ATP7 as an additional assembly site for selected
MIC2875 and MIC2876 device families available in 8L UDFN
(2x2x0.6mm) package.**

Purpose: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

CCB No.: 7580

<u>Misc.</u>	Assembly site	ATP7
	BD Number	TBD
	MP Code (MPC)	TKNB1xxx
	Part Number (CPN)	Various
	MSL information	MSL-1, 260'C
	Assembly Shipping Media (T/R, Tube/Tray)	Cannister
	Base Quantity Multiple (BQM)	3,300
	Reliability Site	MTAI
<u>Lead-Frame</u>	Paddle size	67x39mils
	Material	C7025
	DAP Surface Prep	Ring Ag
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes (Half Etch)
	Part Number	101431341
	Lead Plating	MatteSn
	Strip Size	70x250mm
	Strip Density	2496
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	CDF215
	Conductive	Yes
<u>MC</u>	Part Number	G631BQF
<u>PKG</u>	Package Type	UDFN
	Pin/Ball Count	8
	PKG width/size	2x2x0.6mm

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Pkg. Type	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	UNIC	MTAI	UDFN	Standard Pb-free solderability is the requirement.
Backward Solderability	J-STD-002D ;Perform 8 hours steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Backward: Matte tin/ NiPdAu finish, SnPb solder, wetting temp 215°C for SMD.	22	5	1	27	> 95% lead coverage	5	UNIC	MTAI	UDFN	SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	ATP7	ATP7	UDFN	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	ATP7	ATP7	UDFN	30 bonds from a min. 5 devices.
Wire Sweep								ATP7	ATP7	UDFN	
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30	0	5	ATP7	ATP7	UDFN	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	ATP7	ATP7	UDFN	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C	45	5	1	50	0	10	UNIC	MTAI	UDFN	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL1, 260°C	231	15	3	738	0	15	UNIC	MTAI	UDFN	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	UNIC	MTAI	UDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	UNIC	MTAI	UDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at +25°C	77	5	3	246	0	15	UNIC	MTAI	UDFN	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.